To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):
   Laser Technology West, L.L.C.
   Additional name(s) of conveying party(ies) attached? □ Yes ☒ No

3. Nature of conveyance:
   ☒ Security Agreement  □ Merger
   □ Assignment  □ Change of Name
   □ Other __________________________
   Execution Date: 5/2/00

4. Application number(s) or patent number(s):
   If this document is being filed together with a new application, the execution date of the application is: ______
   A. Patent Application No.(s)
      09/108,864  07/01/98
      08/980,386  11/28/97
   B. Patent No.(s)
      5,878,737  03/09/99
      5,964,210  10/12/99
      6,024,080  02/15/00
   Additional numbers attached? □ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:
   Name: Silicon Valley Bank
   Internal Address: Loan Documentation HG150
   Street Address: 3003 Tasman Dr.
   City: Santa Clara  State: CA  ZIP: 95054

6. Total number of applications and patents involved: 5

7. Total fee (37 CFR 3.41): $200
   ☒ Enclosed
   □ Authorized to be charged to deposit account

8. Deposit account number:
   (Attach duplicate copy of this page if paying by deposit account)

   To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.
   Sara E. Lindsey
   Name of Person Signing
   Signature
   Total number of pages comprising cover sheet: 7

Date: 5/12/00
INTELLECTUAL PROPERTY SECURITY AGREEMENT

This Intellectual Property Security Agreement is entered into as of May 2, 2000 by and between SILICON VALLEY BANK ("Bank") and Laser Technology West, LLC ("Grantor").

RECITALS

A. Bank has agreed to make certain Credit Extensions of money and to extend certain financial accommodation to Grantor (the "Loans") in the amounts and manner set forth in that certain Loan and Security Agreement by and between Bank and Grantor dated May 2, 2000 (as the same may be amended, modified or supplemented from time to time, the "Loan Agreement"; capitalized terms used herein are used as defined in the Loan Agreement). Bank is willing to make the Loans to Grantor, but only upon the condition, among others, that Grantor shall grant to Bank a security interest in certain Copyrights, Trademarks, Patents, and Mask Works to secure the obligations of Grantor under the Loan Agreement.

B. Pursuant to the terms of the Loan Agreement, Grantor has granted to Bank a security interest in all of Grantor's right, title and interest, whether presently existing or hereafter acquired, in, to and under all of the Collateral.

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, and intending to be legally bound, as collateral security for the prompt and complete payment when due of its obligations under the Loan Agreement, Grantor hereby represents, warrants, covenants and agrees as follows:

AGREEMENT

To secure its obligations under the Loan Agreement, Grantor grants and pledges to Bank a security interest in all of Grantor's right, title and interest in, to and under its Intellectual Property Collateral (including without limitation those Copyrights, Patents, Trademarks and Mask Works listed on Schedules A, B, C, and D hereto), and including without limitation all proceeds thereof (such as, by way of example but not by way of limitation, license royalties and proceeds of infringement suits), the right to sue for past, present and future infringements, all rights corresponding thereto throughout the world and all re-issues, divisions continuations, renewals, extensions and continuations-in-part thereof.

This security interest is granted in conjunction with the security interest granted to Bank under the Loan Agreement. The rights and remedies of Bank with respect to the security interest granted hereby are in addition to those set forth in the Loan Agreement and the other Loan Documents, and those which are now or hereafter available to Bank as a matter of law or equity. Each right, power and remedy of Bank provided for herein or in the Loan Agreement or any of the Loan Documents, or now or hereafter existing at law or in equity shall be cumulative and concurrent and shall be in addition to every right, power or remedy provided for herein and the exercise by Bank of any one or more of the rights, powers or remedies provided for in this Intellectual Property Security Agreement, the Loan Agreement or any of the other Loan Documents, or now or hereafter existing at law or in equity, shall not preclude the simultaneous or later exercise by any person, including Bank, of any or all other rights, powers or remedies.

IN WITNESS WHEREOF, the parties have cause this Intellectual Property Security Agreement to be duly executed by its officers thereunto duly authorized as of the first date written above.
Address of Grantor:

Murray
1605 South Murphy Boulevard
Colorado Springs, CO 80916
Attn: John B. Hodsdon

GRANTOR:
Laser Technology West, LLC
By: [Signature]
Title: President

Address of Bank:

4430 Arapahoe Ave., Ste. 225
Boulder, CO 80303
Attn: Mike Devery

BANK:
SILICON VALLEY BANK
By: [Signature]
Title: Senior Vice Pres & Manager
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<td>PATENT # 5,964,210 DATED 10.12.99</td>
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<td>PATENT # 6,024,030 DATED 2.15.2000</td>
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EXHIBIT D

Mask Works

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